

SPECIFICATIONS

Mechanical

Socket Engagement Force: 3.9kgf max.
Socket Disengagement Force: 1kgf max.
Durability: 20 Cycles min.
Solder Ball Shear Force: 500gf min.

LGA/BGA CPU Socket

LGA SMT Type

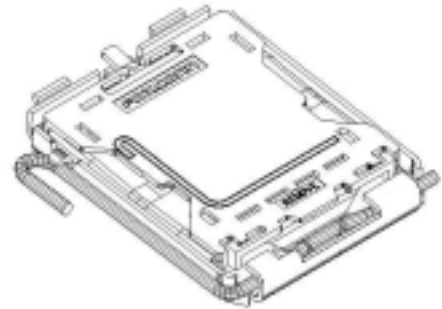
1.09X1.17mm[.043 X.046"] Pitch
771 Pos.

Electrical

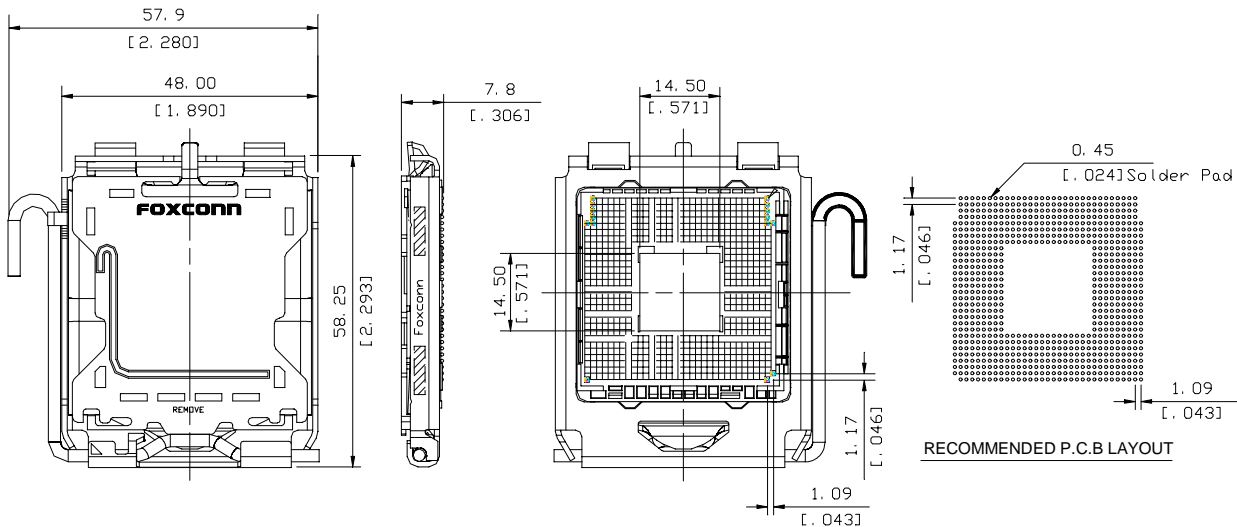
Final Averaged Contact Resistance
(average of minimum 12pin/chian): 15.2 mΩ max.
Final Max. Chain Contact Resistance: 28 mΩ max.
Insulation Resistance: 800mΩ min.
Dielectric Withstanding Voltage: 360 V RMS min.

Physical

Socket Body: Thermoplastic, UL 94V-0 rated, Black Color
PnP Cap: Thermoplastic, UL 94V-0 rated, Black Color
Load Plate: Stainless Steel
Stiffener: Stainless Steel
Load Lever: Stainless Steel
Contact: Copper Alloy
Plating: See "ORDERING INFORMATION"



DRAWING



ORDERING INFORMATION

PRODUCT NO.: P E 0771 2 7- 10 4 1- 0 1 F

- Actual Loading Contact 0771=771 Contact
- Solder Ball Type: 2=Sn/Ag/Cu Solder Ball
- Gold Plating On Contact Area 7=15u" Gold Plating On Contact Area
- Grid Array Type 09,10=33X30 With 15X14 Grid Depopulation in the center
- F=Lead Free
- Identification Code
- Pick Up Cap Design 1=Removal Table Is Flat
- Package 0=Hard Tray
- Material Of Contact 1=Copper Alloy
- Material / Color Of Insul: 4=Thermoplastic Black